

R&D in RF Superconductivity

Research Axis :

Chemistry

New chemical treatments
Electrochemistry

Thermal treatment

Purification annealing
Grain boundaries behaviour (segregation, resistivity)

Surface analyses

Kapitza resistance
Nuclear microprobe, SIMS, microscopy (opt, MEB, STM, AFM), roughness...

Field emission :

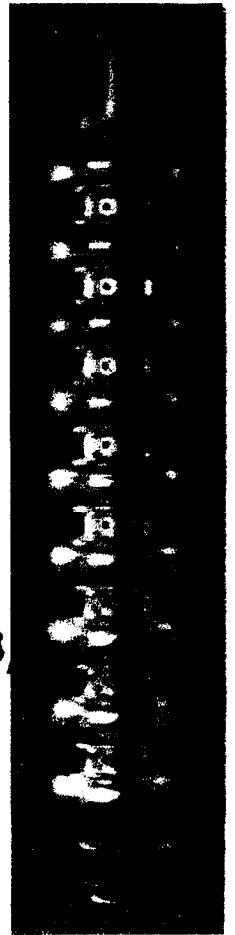
Surfaces under high field studied by :
X Ray interferometry
Scanning Tunneling Microscope

Fabrication costs

New fabrication techniques \Rightarrow welding, hydroforming , plasma deposition (copper on Nb)
Thin films (magnetron sputtering of Nb on copper)

New activities

$\beta < 1$ Cavities for high power proton



Fabrication Techniques

Standard Technique

- 9-cell Cavity. bulk Nb : ~ iris, equator, clan welding ; stiffeners welding .

New techniques (bulk Niobium)

- Hydroforming : welding suppression (iris, equator)
- Plasma Cu deposition : in place of stiffeners, allows to reduce Nb thickness

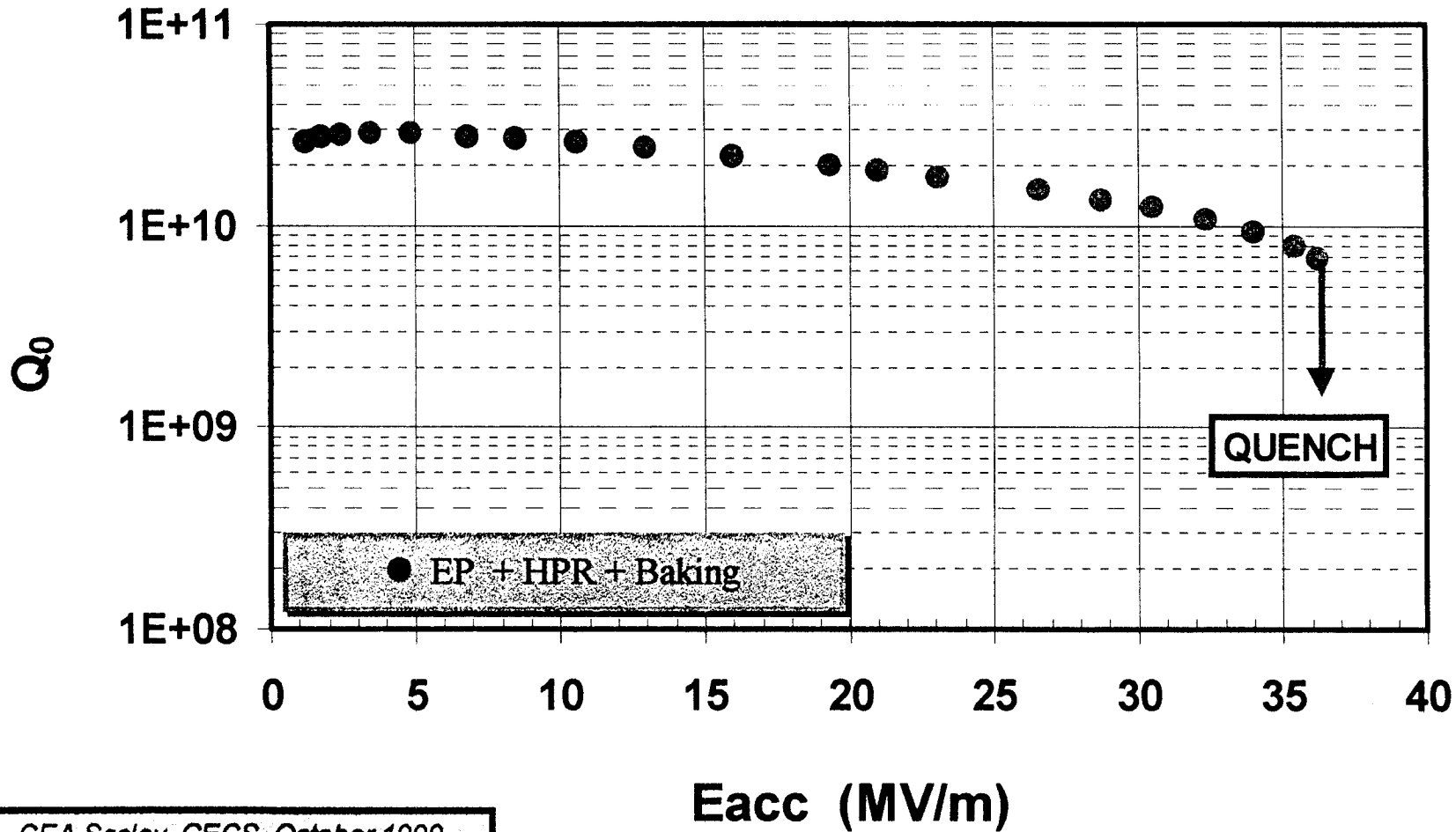
Thin films

- magnetron sputter coated Nb/Cu (and NbTiN/Cu)

Cavity D122 / 1S2 Electropolishing

DESY Cavity, EP at CERN, Test at SACLAY

F = 1.3 GHz, T = 1.7 K



FORMING SEAMLESS CAVITIES

- **Hydroforming**

2-cells cavities from Nb tubes at SIBB Indust.

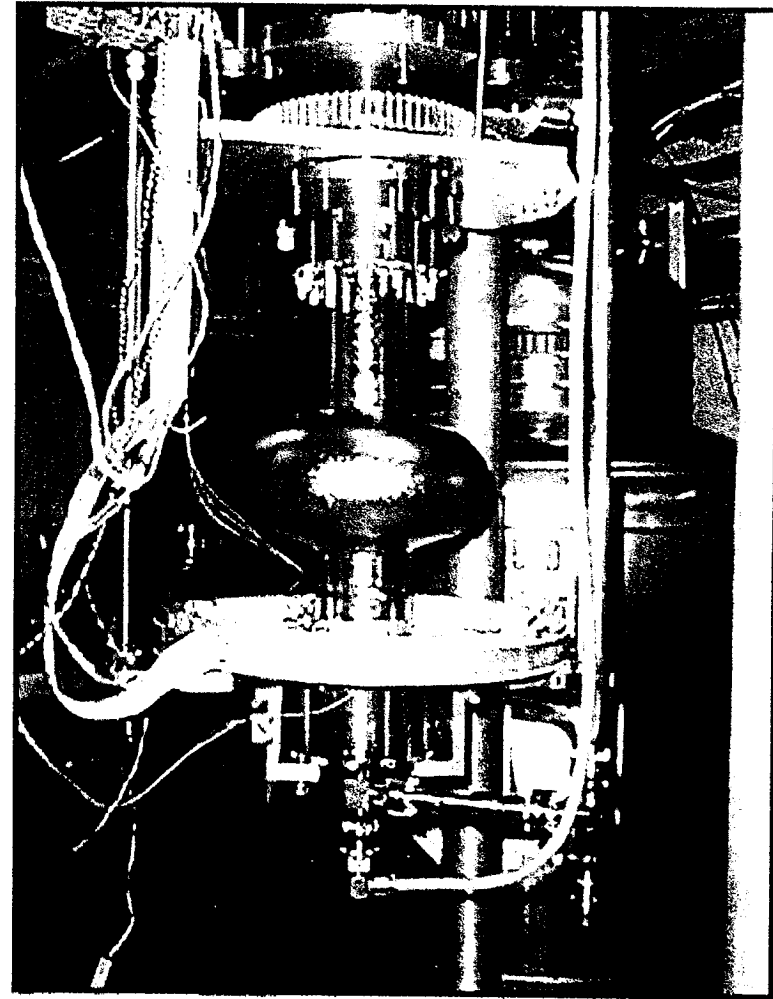
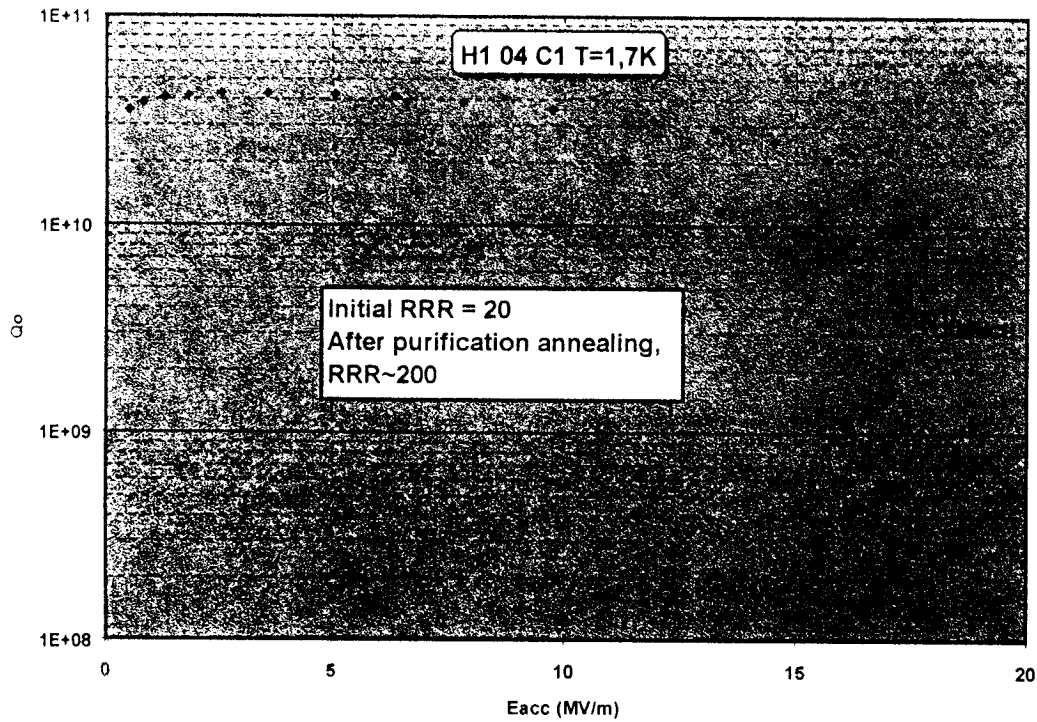
$\varnothing = 51.7 \text{ mm}$ - 2 mm thickness $r/a = 2/1$ -
annealing 800° at 40% deformation

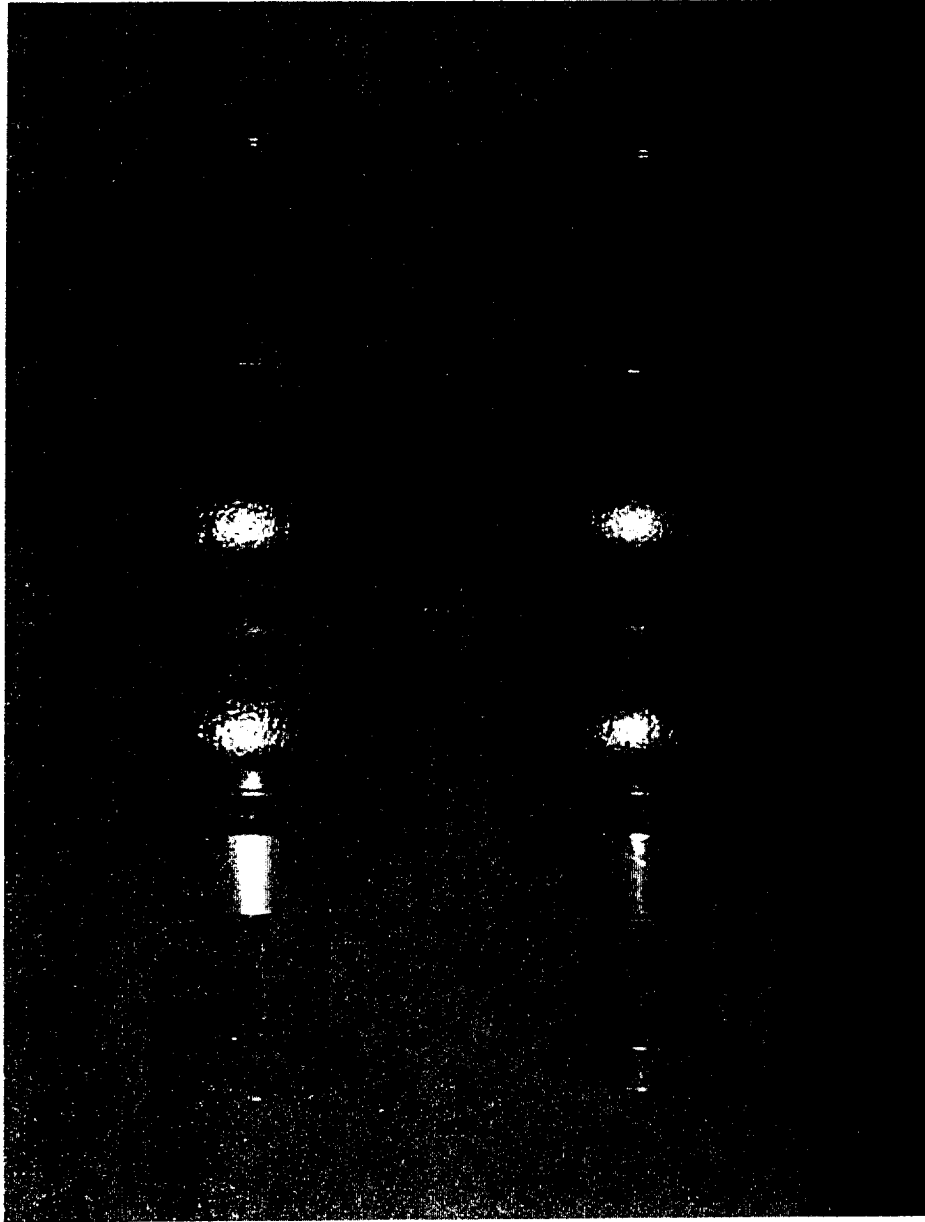
- **Hot forming**

most appropriate temperature found to be 900
and 1400°

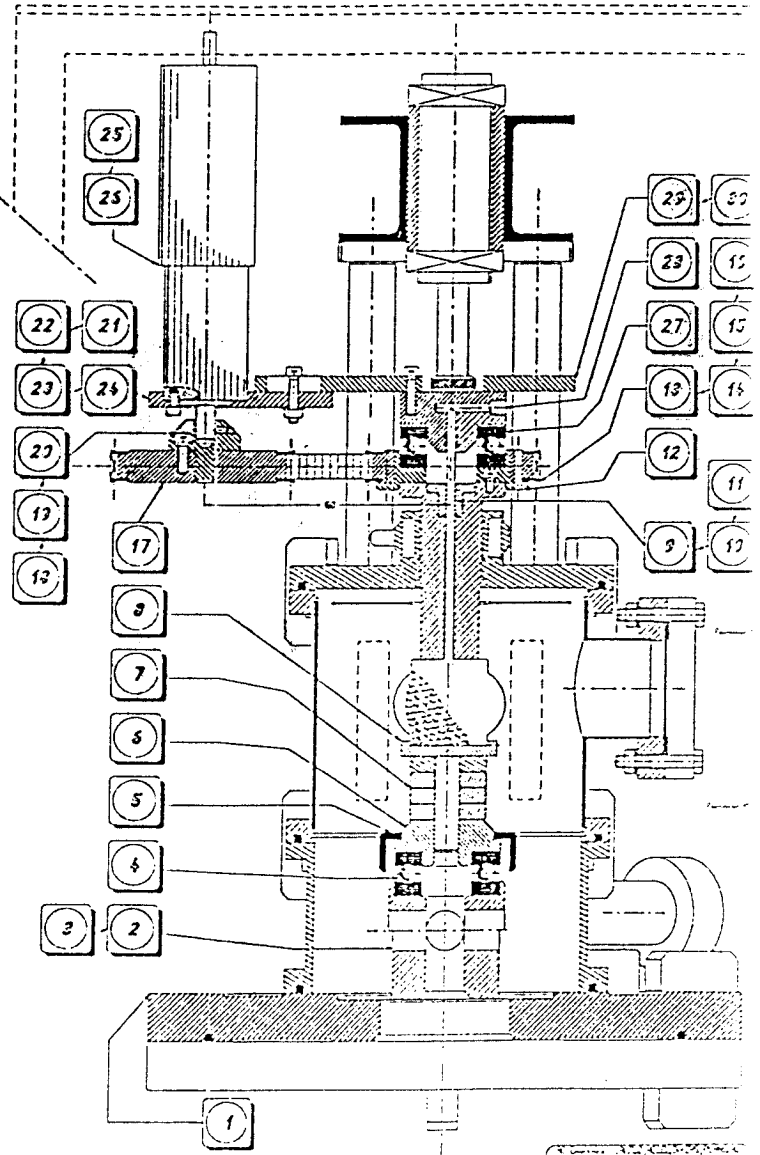
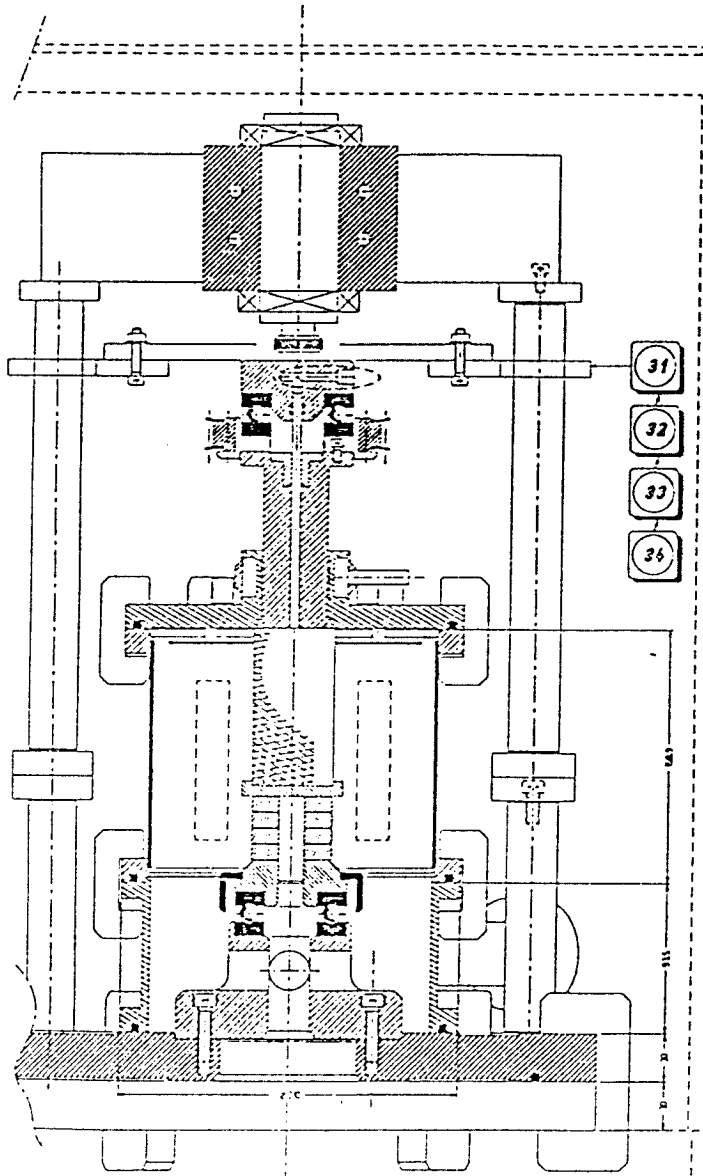
mechanical behaviour however show max.
deformations below 1200°

Hydroforming





- First annealing at 900° before delivery to the company
- First two-cell cavities hydroformed



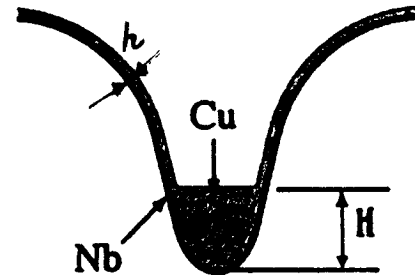
УНИВЕРСАЛЬНЫЙ
СТАНОК

Formage à chaud Température 850 °
Tube Niobium épaisseur 0,5 mm - diamètre 38 mm
Pression interne 20 bar - Poussée axiale 500 kg



THE ALTERNATIVE STIFFENING SCHEME

The principle: add a copper layer onto the cavity outer wall by thermal spraying.



The goal: find a good technical solution, of high stiffening capability and not affecting the cavity performances (Q_0 level and max field)

The advantages: industrial (fully automated process, compatible with large scale production), lower cost (reducing Nb thickness, avoiding expensive EB weldings of stiffening rings), could be efficient even for high gradients (40 MV/m).

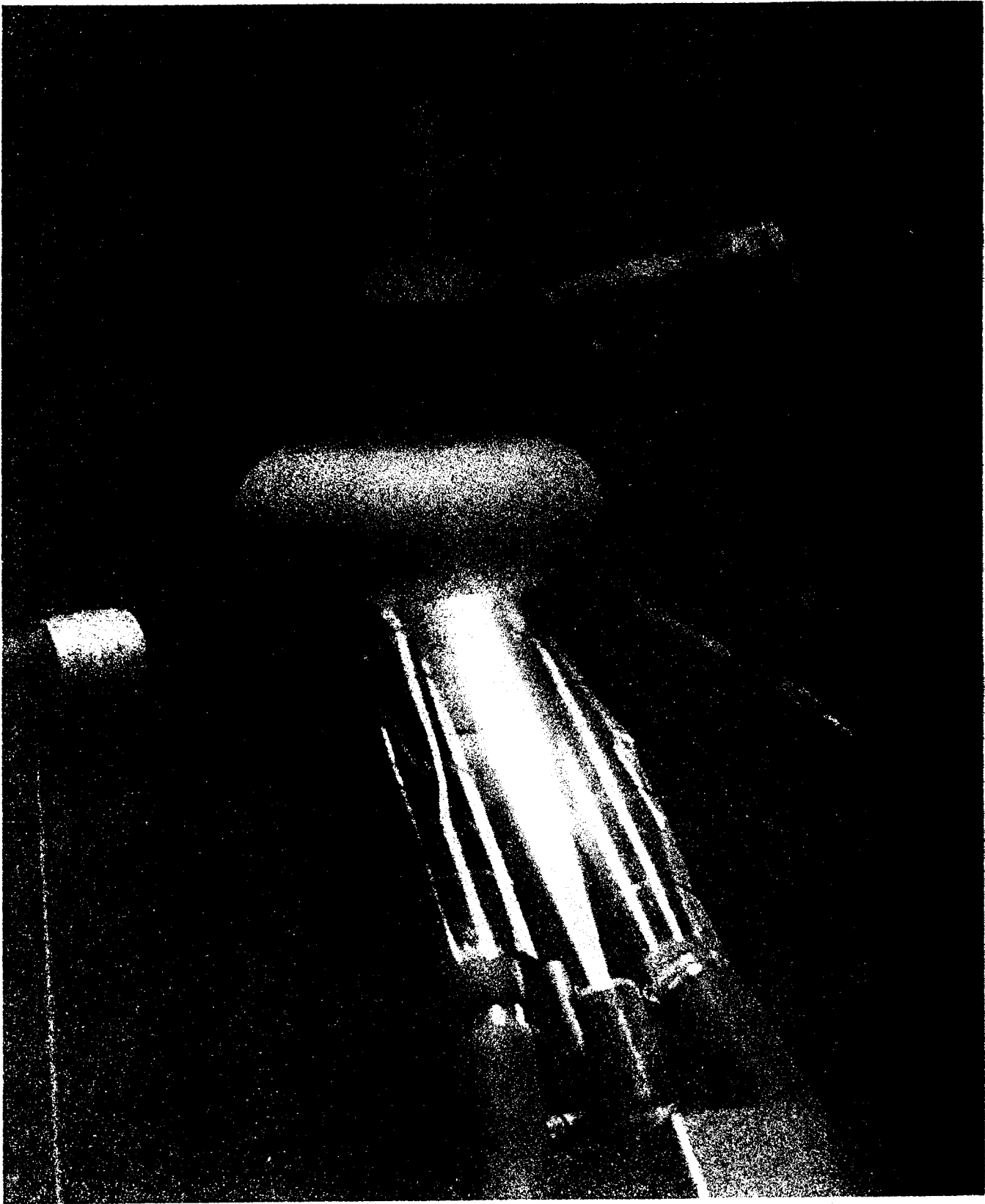


THE THERMAL SPRAYING TECHNIQUES

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A lot of different thermal spraying techniques exists, each of them can produce coatings with specific properties. The main differences are the heat source and the environment.

Process	Flame Spraying (FS)	High Velocity Oxy-Fuel (HVOF)	Atmospheric Plasma Spraying (APS)	Controlled Atmosphere Plasma Spraying (CAPS)	Vacuum Plasma Spraying (VPS)	Arc Spraying (AS)
Heat source	Combustion of fuel gas in oxygen	Combustion of fuel gas in oxygen at high pressure	Plasma (mixture of Ar/H ₂ , Ar/He or Ar/N ₂)	Plasma (mixture of Ar/H ₂ , Ar/He or Ar/N ₂)	Plasma (mixture of Ar/H ₂ , Ar/He or Ar/N ₂)	Arc heating (consumable electrodes)
Heat source temperature	3000 - 3500 K	3000 - 3500 K	10000 K - 15000 K	10000 K - 15000 K	10000 K-15000 K	-
Exhaust jet speed	80 - 100 m/s	1500-2000 m/s	500 - 800 m/s	500 - 800 m/s	1500 - 3000 m/s	particle speed < 150 m/s
Particle size	Powder: 5-100 μm Wire diameter 3-6 mm	5 - 50 μm	5 - 100 μm	5 - 100 μm	5 - 20 μm	Wire diameter: 2 - 5 mm
Atmosphere	Air	Air	Air	Inert Gas Ar, He, N ₂	vacuum (50 mbar)	Air
Porosity	10 - 20 %	< 5 % < 1 % possible	1- 10 % typical	1- 10 %	< 2 %	10 -20 %
Bonding strength	30 MPa typical 70 MPa max.	> 60 MPa typical 100 MPa achievable	20 - 80 MPa	20 - 50 MPa 80 MPa achievable	> 80 MPa	10-30 MPa typical
Remarks	Industrial, high oxidation	Industrial, high bonding strength	Industrial, high oxidation	Low oxidation homogeneous coating	Low oxidation, high bonding strength	Industrial, poor coating properties





COATINGS CHARACTERISTICS

Thermal and mechanical characteristics of coatings for various deposition process

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(An X means no sample available for measurement)

Cu APS Meaders	3	25	≈ 20/30%	$4.0 \cdot 10^{-4}$ (2 mm)	3	1.55	≈ 75	Stiffening 33 MV/m
Cu CAPS CEA	X	≈ 60	9.8 %	$3.9 \cdot 10^{-4}$ (2 mm)	3	X	≈ 100	Stiffening > 35 MV/m
Cu HVOP Yermans	3	53	2.6 %	$> 1.43 \cdot 10^{-3}$ (3 mm)	> 10	0.19	≈ 100	Heat transfert < 30 MV/m
Ti APS SIGN	3	18	≈ 20/30%	$5.0 \cdot 10^{-4}$ (2 mm)	3.5	X	X	Stiffening < 32 MV/m
Cu APS Evry	4	60	1-2 %	$> 1.8 \cdot 10^{-3}$ (3 mm)	> 16	0.22	≈ 100	Heat transfert < 25 MV/m
Ultimate Goal		95		$4.2 \cdot 10^{-4}$	3	4.8 (for $e_{Cu}=2mm$ & no He penetration)	80 -100	40 MV/m

The room-temperature electrical resistivity is a factor 5 lower than the bulk copper resistivity.

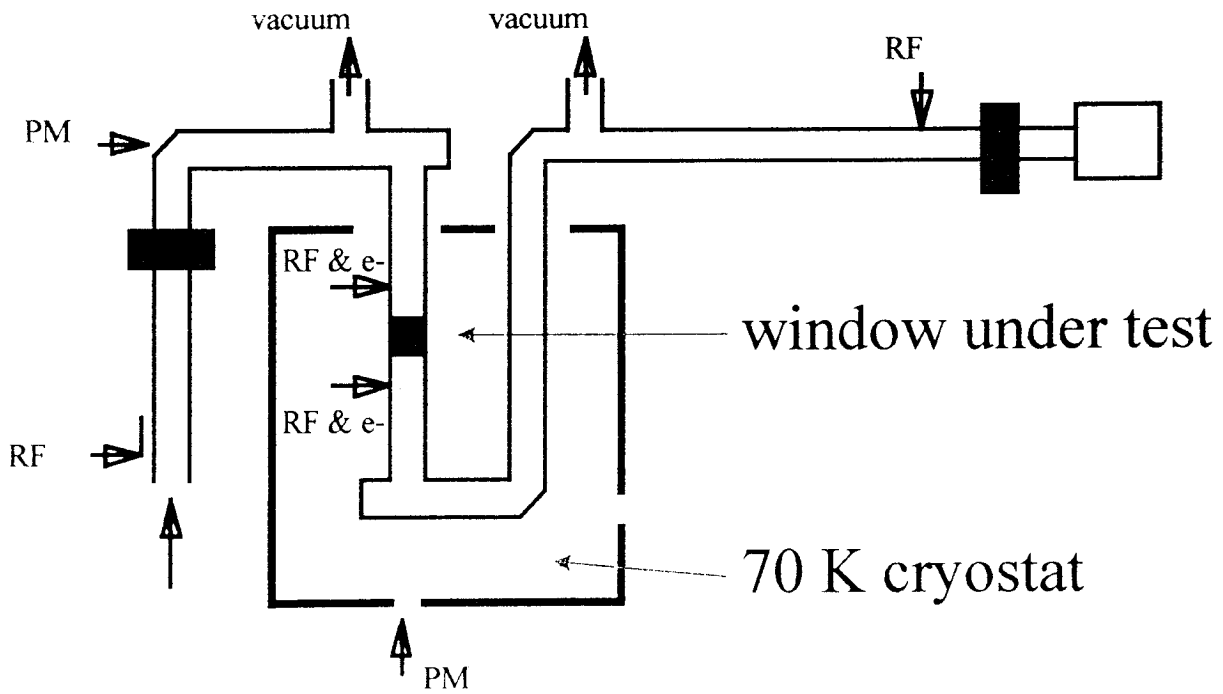
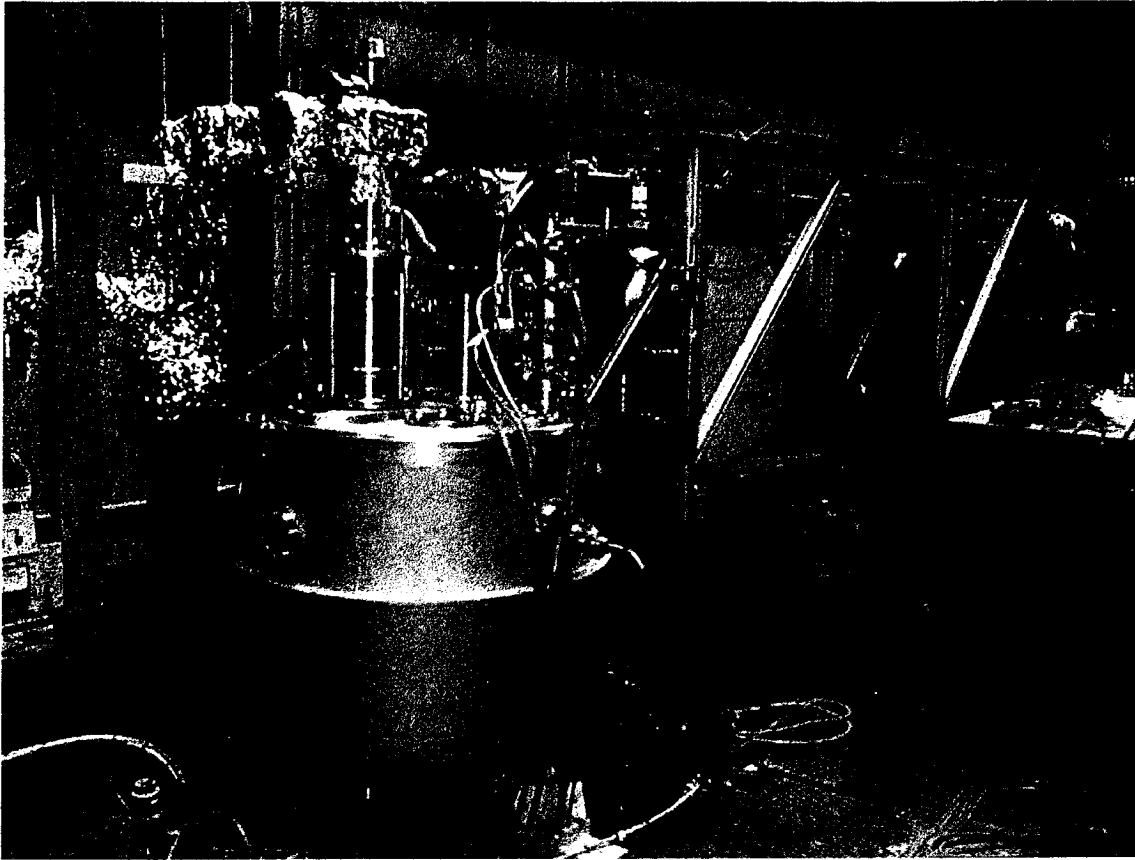
The oxide content of the copper coating obtained by the APS (Evry) process was measured to be 12 % (quite high).

➔ **The coating thermal conductivity is much lower than the bulk material one, probably due to the high oxidation. As showed with Ti, the poor coating thermal conductivity is short-circuited by the superfluid helium when the porosity rate is high.**

The CAPS process (under inert gaz), thanks to the reduced oxidation, seems to be a possible solution for TESLA -800 cavity stiffening (34 MV/m).

SACLAY-ORSAY COUPLER TEST STAND

M. Desmons (Saclay)



$\lambda/2$ window tests results

C. Travier (Saclay)

Advantages

- easiest concept
 - low cost
 - robustness
 - E field parallel to ceramic
- ➔ no multipactor

Drawbacks

- maximum field at brazing point
- high dielectric losses
- direct view of cavity electrons

Test results

1 MW, 1.3 ms, 0.1 Hz
at 300 K and 80 K

no multipactor on window
no problems with max field on brazing
dielectric losses depends on position
in SW regime (factor 9 between
max and min)



Travelling wave window

C. Travier (Saclay)

Advantages

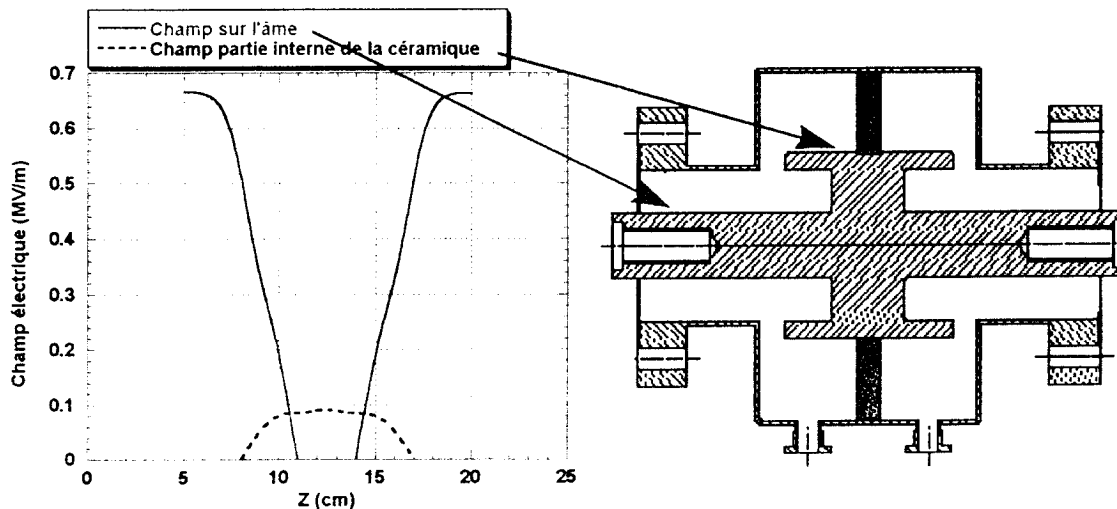
- pure TW in ceramic
 - no direct view of cavity electrons
 - low field at brazing point
 - low dielectric loss
 - great flexibility in parameter choice
 - moderate cost
 - E field parallel to ceramic
- ➔ no multipactor

Drawbacks

- large diameter
 - high field on noses
- difficult to clean

Test results

1 MW, 1 ms, 0.1 Hz
@ 300 k and 100 K.
- no multipactor



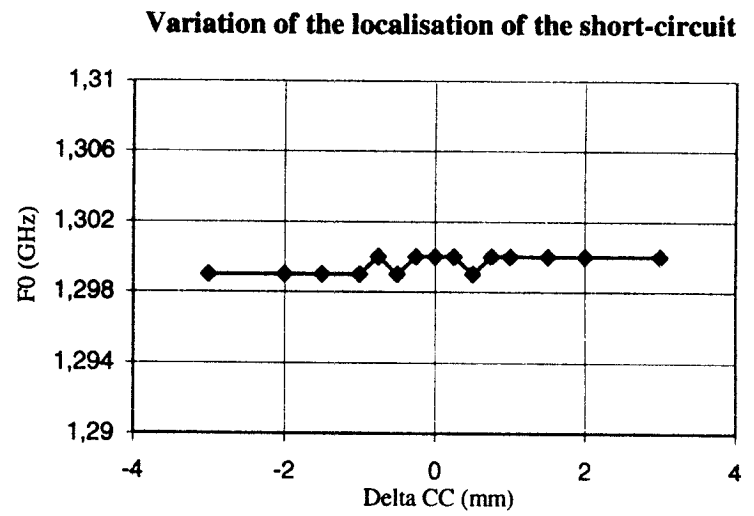
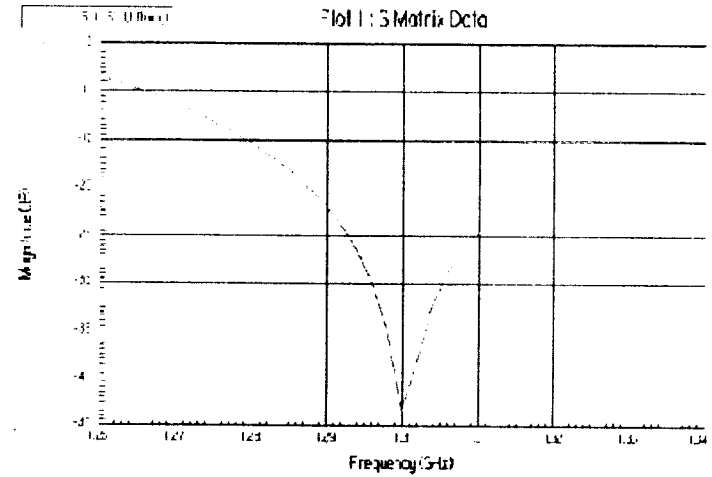
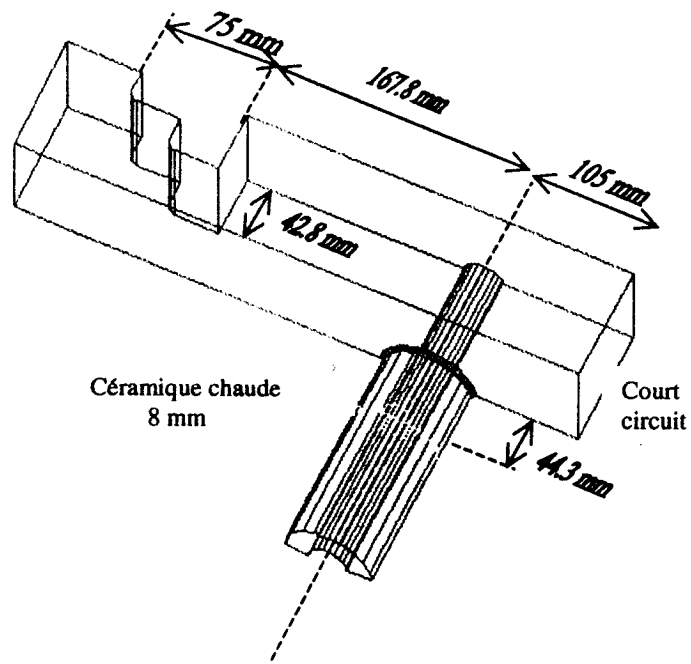
See poster on Wednesday WEPO15

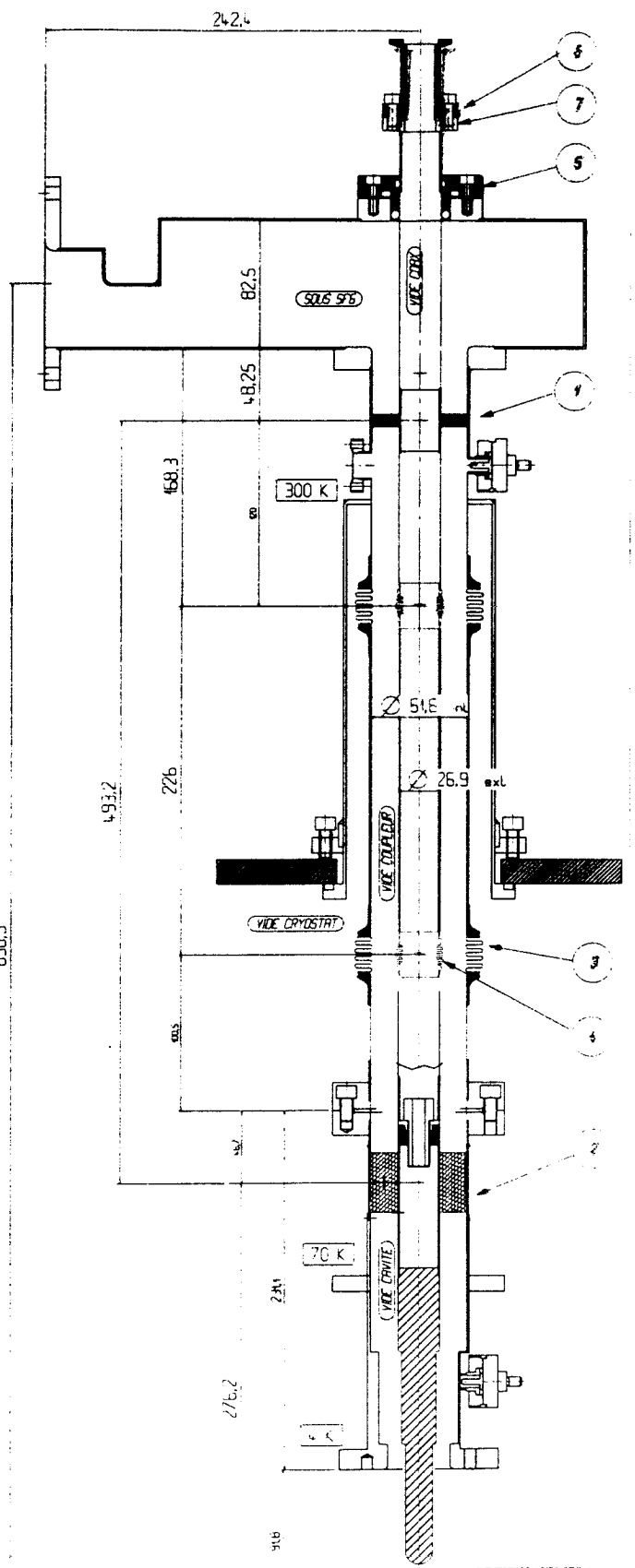
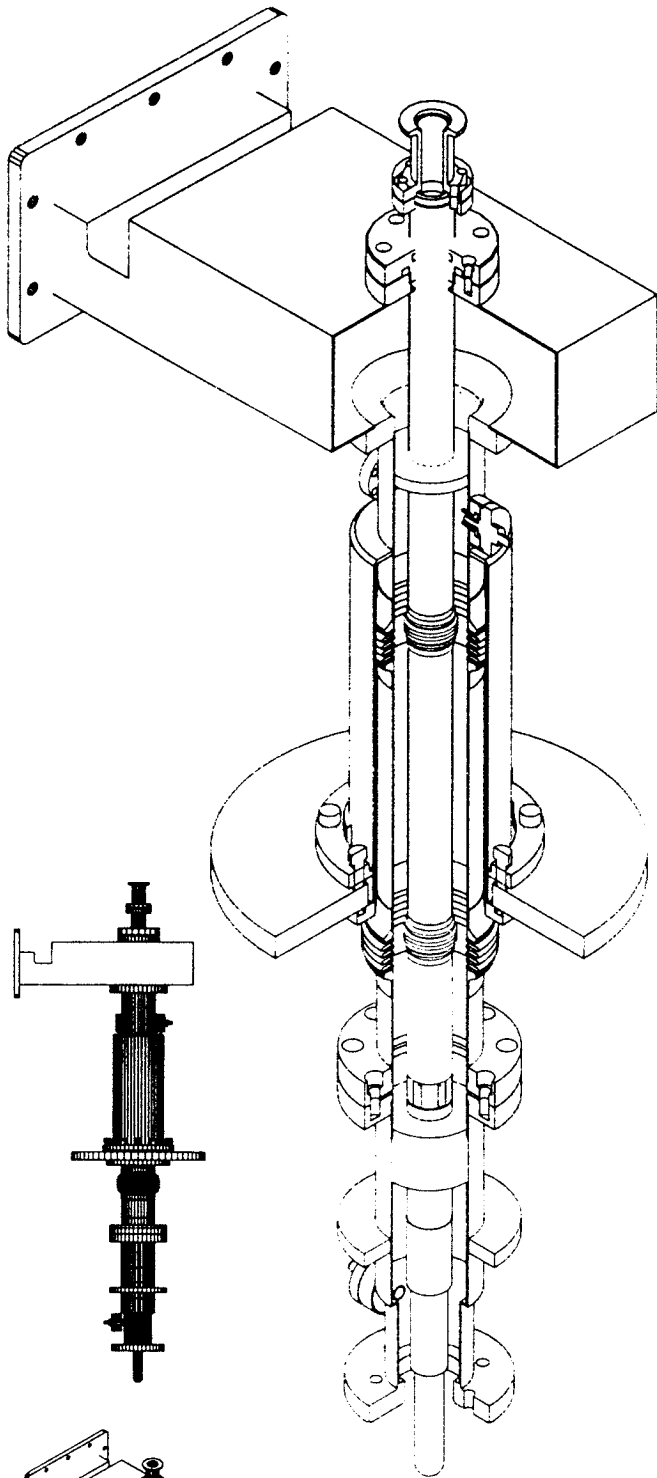
ON GOING STUDIES

- TiN coating
- multipacting simulations
- metal/ceramic bonding

HIGH POWER COUPLERS

- Goals were to build a transition operated with neutral gas pressure and that integrates the warm ceramic window
- The proposed transition uses a thin ceramic and is matched at 1.3 GHz using reduced sizes waveguides
- The transition can be upgraded to include a DC bias
- Mechanical tolerances are relaxed and cost is reduced





7	25-PIED 26- EEDNRE BRIDE	REAL		
	JOINT R 6	PILOH		
6	25-PIED 26- LIPPE 0725	REAL		
	JOINT R 20			
5	25-PIED 26- BRIDE	REAL		
	VIDE Cw 6-15			
	JOINT R 20	PILOH		
	JOINT R 25	PILOH		
4	25-PIED 26- BRIDE	REAL		
	VIDE Cw 6-15			
3	25-PIED 26- BRIDE	REAL		
	VIDE Cw 6-15			
2	25-PIED 26- BRIDE	REAL		
	VIDE Cw 6-15			
1	25-PIED 26- BRIDE	REAL		
	VIDE Cw 6-15			

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